

## 1. General description

High voltage, high speed, planar passivated NPN power switching transistor with integrated anti-parallel E-C diode in a SOT78 (TO220AB) plastic package.

## 2. Features and benefits

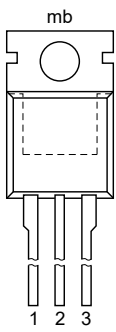
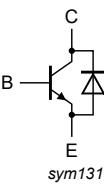
- Fast switching
- High voltage capability
- Integrated anti-parallel E-C diode
- Very low switching and conduction losses

## 3. Applications

- DC-to-DC converters
- Electronic lighting ballasts
- Inverters
- Motor control systems

## 4. Pinning information

Table 1. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p>mb</p> <p>1 2 3</p> <p><b>TO-220AB (SOT78)</b></p>	 <p>sym131</p>
2	C	collector		
3	E	emitter		
mb	C	mounting base; connected to collector		

## 5. Ordering information

Table 2. Ordering information

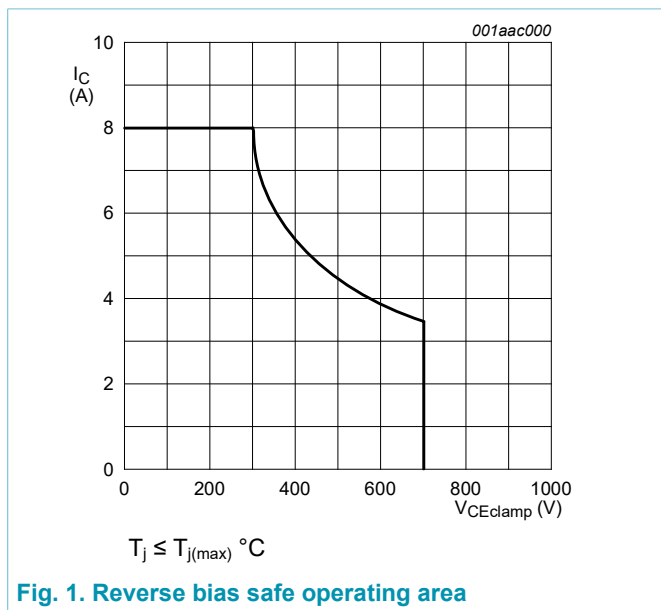
Type number	Package		
	Name	Description	Version
BUJD203A	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 6. Limiting values

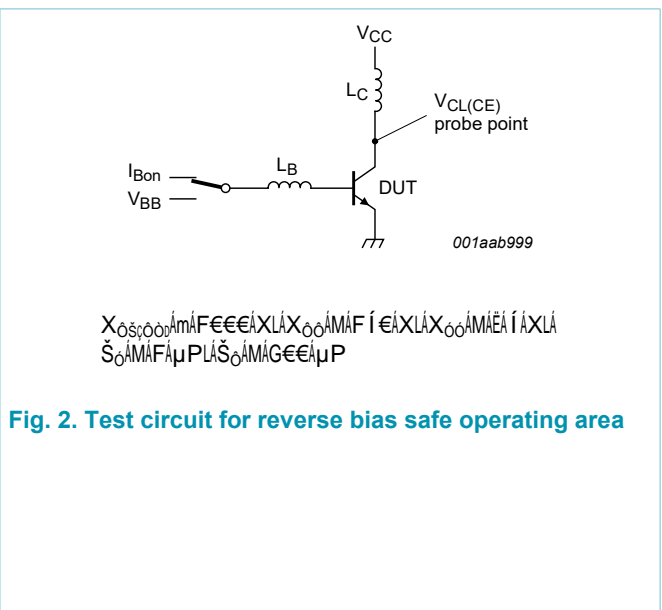
**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

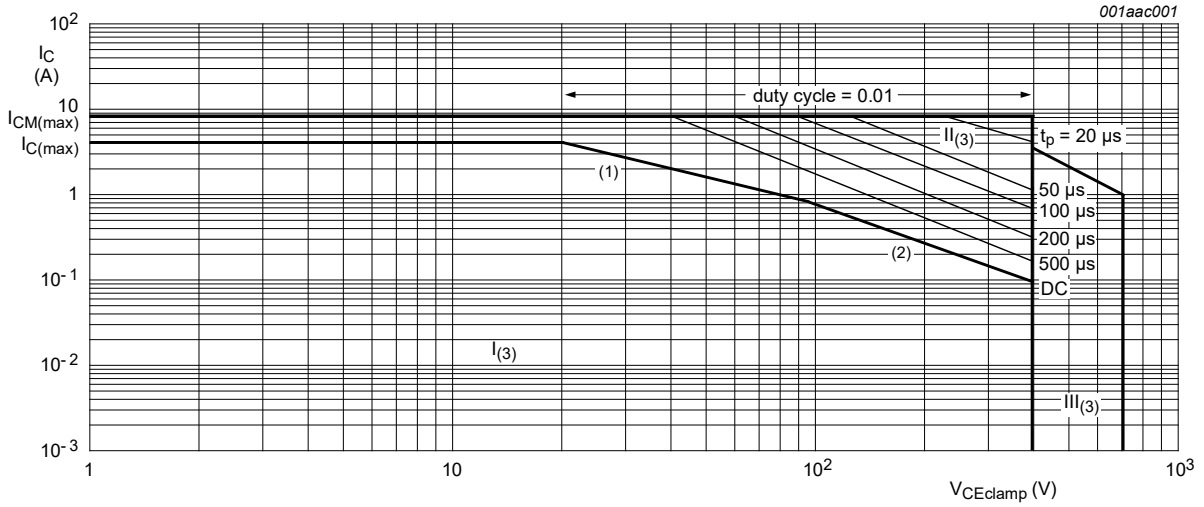
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$	-	850	V
$V_{CBO}$	collector-base voltage	$I_E = 0\text{ A}$	-	850	V
$V_{CEO}$	collector-emitter voltage	$I_B = 0\text{ A}$	-	425	V
$I_C$	collector current	DC; Fig. 1; Fig. 2; Fig. 3	-	4	A
$I_{CM}$	peak collector current	Fig. 1; Fig. 2; Fig. 3	-	8	A
$I_B$	base current	DC	-	2	A
$I_{BM}$	peak base current		-	4	A
$P_{tot}$	total power dissipation	$T_{mb} \leq 25\text{ °C}$ ; Fig. 4	-	80	W
$T_{stg}$	storage temperature		-65	150	°C
$T_j$	junction temperature		-	150	°C



**Fig. 1. Reverse bias safe operating area**

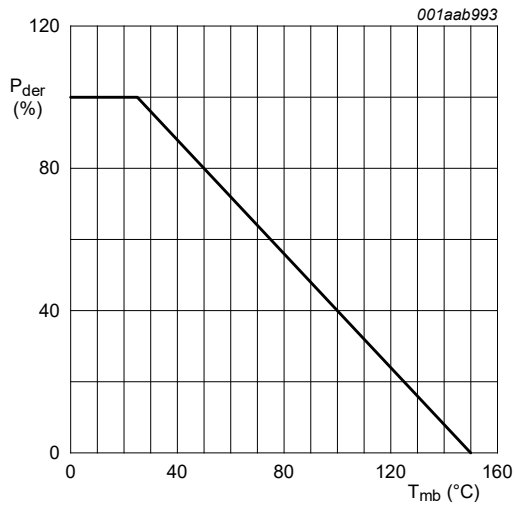


**Fig. 2. Test circuit for reverse bias safe operating area**



- 1)  $P_{tot}$  maximum and  $P_{tot}$  peak maximum lines
- 2) Second breakdown limits
- 3) I = Region of permissible DC operation  
 II = Extension for repetitive pulse operation  
 III = Extension during turn-on in single transistor converters provided that  $R_{BE} \leq 100 \Omega$  and  $t_p \leq 0.6 \mu s$

Fig. 3. Forward bias safe operating area for  $T_{mb} \leq 25^\circ C$



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100\%$$

Fig. 4. Normalized total power dissipation as a function of mounting base temperature

### 7. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	1.56	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

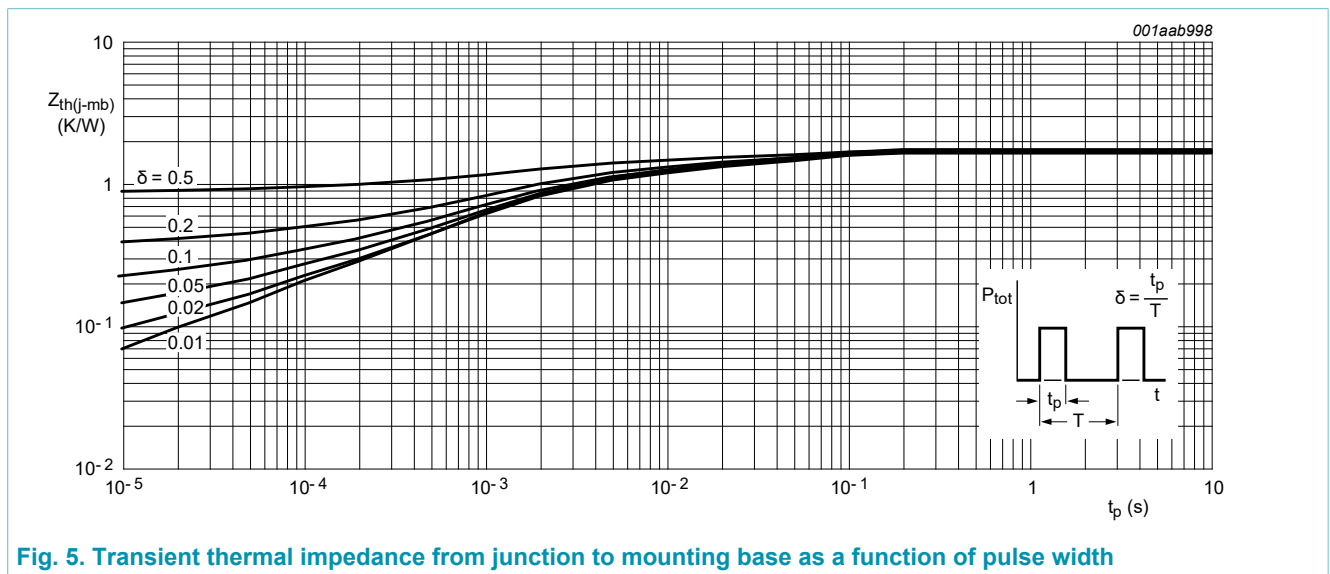


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse width

## 8. Characteristics

Table 5. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Static characteristics</b>							
$I_{CES}$	collector-emitter cut-off current (base shorted)	$V_{BE} = 0\text{ V}; V_{CE} = 850\text{ V}; T_j = 125\text{ }^\circ\text{C}$	[1]	-	-	2	mA
		$V_{BE} = 0\text{ V}; V_{CE} = 850\text{ V}; T_j = 25\text{ }^\circ\text{C}$	[1]	-	-	1	mA
$I_{CBO}$	collector-base cut-off current (emitter open)	$V_{CB} = 850\text{ V}; I_E = 0\text{ A}$	[1]	-	-	1	mA
$I_{CEO}$	collector-emitter cut-off current (base open)	$V_{CE} = 425\text{ V}; I_B = 0\text{ A}$	[1]	-	-	0.1	mA
$I_{EBO}$	emitter-base cut-off current (collector open)	$V_{EB} = 7\text{ V}; I_C = 0\text{ A}$		-	-	10	mA
$V_{CE0sus}$	collector-emitter sustaining voltage (base open)	$I_B = 0\text{ A}; I_C = 10\text{ mA}; L_C = 25\text{ mH};$ <a href="#">Fig. 6</a> ; <a href="#">Fig. 7</a>		400	450	-	V
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 3\text{ A}; I_B = 0.6\text{ A};$ <a href="#">Fig. 8</a> ; <a href="#">Fig. 9</a>		-	0.29	1	V
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 3\text{ A}; I_B = 0.6\text{ A};$ <a href="#">Fig. 10</a>		-	0.99	1.5	V
$V_F$	forward voltage	$I_F = 2\text{ A}; T_j = 25\text{ }^\circ\text{C}$		-	1.04	1.5	V
$h_{FE}$	DC current gain	$I_C = 1\text{ mA}; V_{CE} = 5\text{ V}; T_{mb} = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>		10	15	32	
		$I_C = 500\text{ mA}; V_{CE} = 5\text{ V}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>		13	21	32	
		$I_C = 2\text{ A}; V_{CE} = 5\text{ V}; T_{mb} = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>		11	16	22	
		$I_C = 3\text{ A}; V_{CE} = 5\text{ V}; T_{mb} = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 11</a>		-	12.5	-	
<b>Dynamic characteristics</b>							
$t_{on}$	turn-on time	$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; I_{Boff} = -0.5\text{ A};$ $R_L = 75\text{ }\Omega; T_j = 25\text{ }^\circ\text{C};$ resistive load; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	0.52	0.6	$\mu\text{s}$
$t_s$	storage time	$I_C = 2\text{ A}; I_{Bon} = 0.4\text{ A}; V_{BB} = -5\text{ V};$ $L_B = 1\text{ }\mu\text{H}; T_j = 25\text{ }^\circ\text{C};$ inductive load; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>		-	2.7	3.3	$\mu\text{s}$
		$I_C = 2\text{ A}; I_{Bon} = 0.4\text{ A}; V_{BB} = -5\text{ V};$ $L_B = 1\text{ }\mu\text{H}; T_j = 100\text{ }^\circ\text{C};$ inductive load; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>		-	1.2	1.4	$\mu\text{s}$
		$I_C = 2\text{ A}; I_{Bon} = 0.4\text{ A}; V_{BB} = -5\text{ V};$ $L_B = 1\text{ }\mu\text{H}; T_j = 100\text{ }^\circ\text{C};$ inductive load; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>		-	-	1.8	$\mu\text{s}$
$t_f$	fall time	$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; I_{Boff} = -0.5\text{ A};$ $R_L = 75\text{ }\Omega;$ resistive load; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>		-	0.3	0.35	$\mu\text{s}$
		$I_C = 2\text{ A}; I_{Bon} = 0.4\text{ A}; V_{BB} = -5\text{ V};$ $L_B = 1\text{ }\mu\text{H};$ inductive load; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>		-	-	0.12	$\mu\text{s}$
				-	0.03	0.06	$\mu\text{s}$

[1] Measured with half-sine wave voltage (curve tracer)

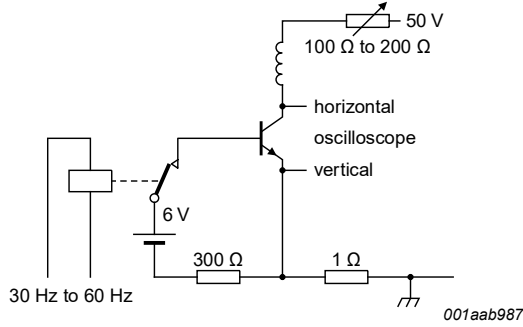


Fig. 6. Test circuit for collector-emitter sustaining voltage

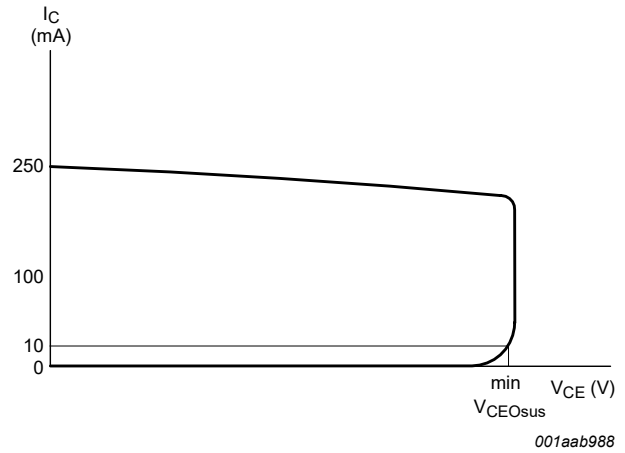


Fig. 7. Oscilloscope display for collector-emitter sustaining voltage test waveform

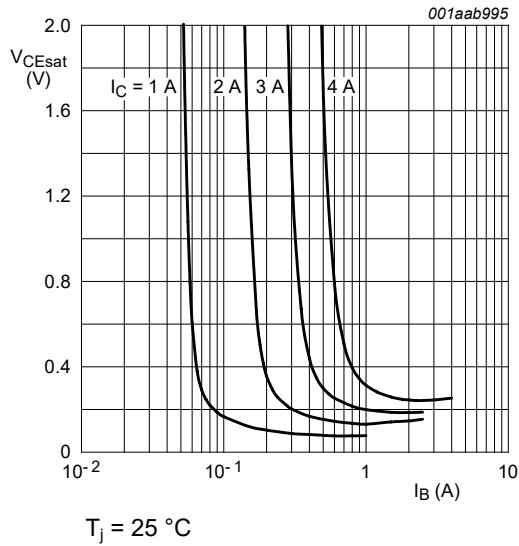


Fig. 8. Collector-emitter saturation voltage as a function of base current; typical values

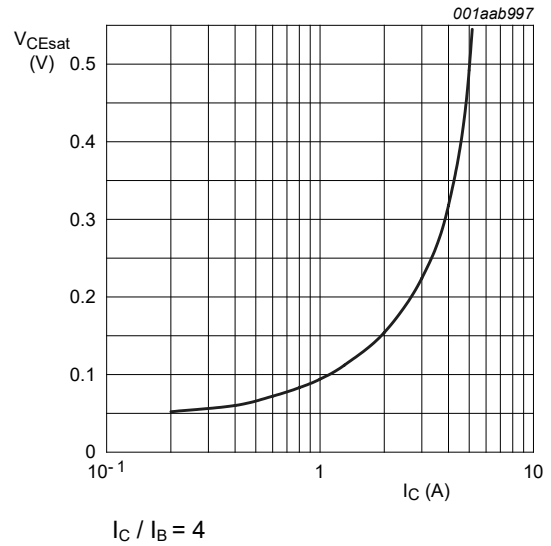


Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values

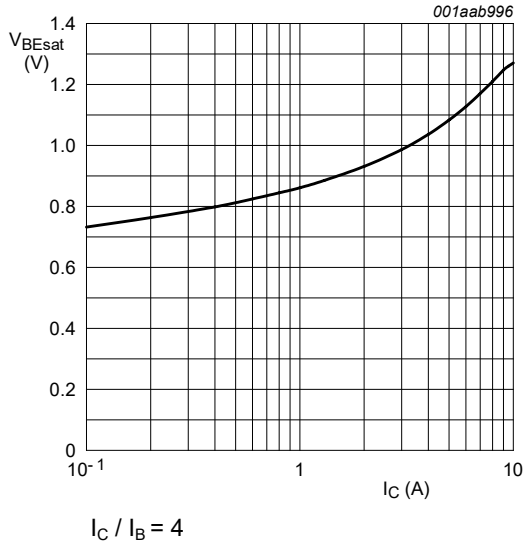


Fig. 10. Base-emitter saturation voltage as a function of collector current; typical values

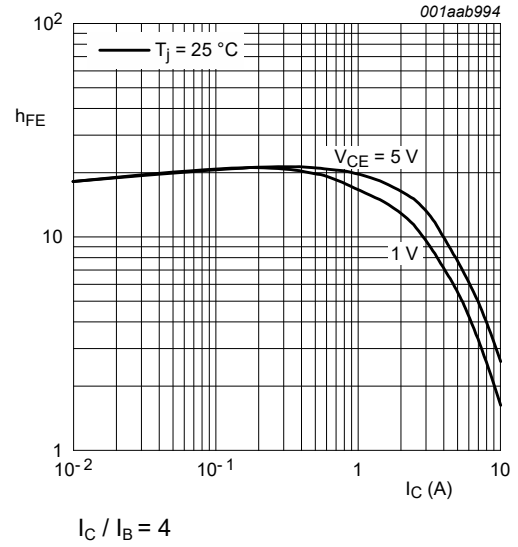
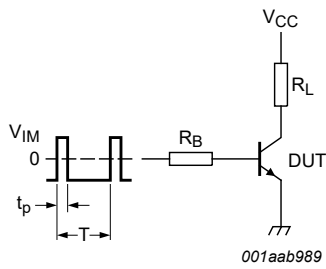


Fig. 11. DC current gain as a function of collector current; typical values



$V_{IM} = -6$  to  $+8$  V;  $V_{CC} = 250$  V;  $t_p = 20$   $\mu$ s;  $\delta = t_p/T = 0.01$   
 $R_B$  and  $R_L$  calculated from  $I_{Con}$  and  $I_{Bon}$  requirements.

Fig. 12. Test circuit for resistive load switching

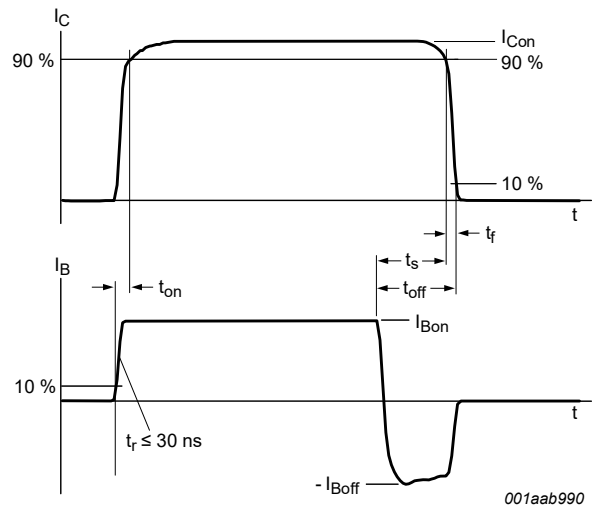
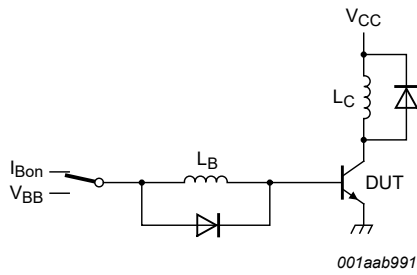


Fig. 13. Switching times waveforms for resistive load





$V_{CC} = 300\text{ V}; V_{BB} = -5\text{ V}; L_C = 200\ \mu\text{H}; L_B = 1\ \mu\text{H}$

Fig. 14. Test circuit for inductive load switching

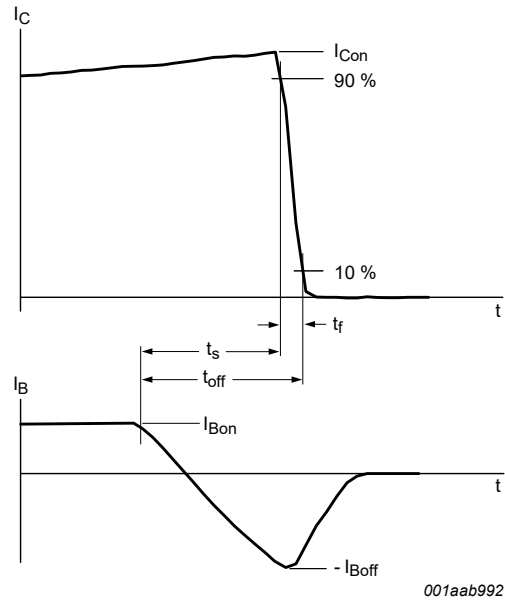
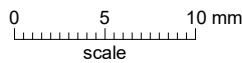
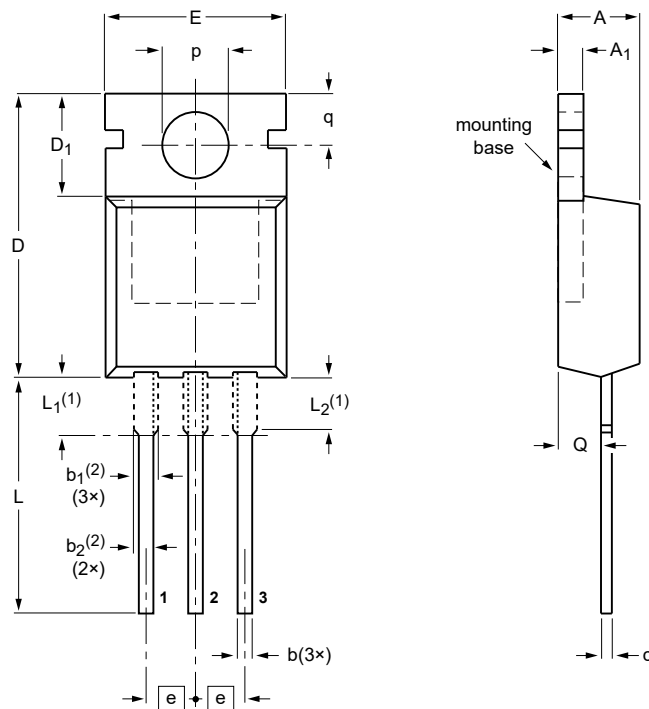


Fig. 15. Switching times waveforms for inductive load

### 9. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB SOT78



**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub> ( <sup>2</sup> )	b <sub>2</sub> ( <sup>2</sup> )	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub> ( <sup>1</sup> )	L <sub>2</sub> ( <sup>1</sup> ) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

**Notes**

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13

Fig. 16. Package outline TO-220AB (SOT78)

## 10. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
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